TE Internal #: 1-1337604-0

SMB Connector, Jack, 50 ohm, Snap-Fit, 4 GHz, Cable-to-Cable, 1

Position, Printed Circuit Board, Board Mount, -65 – 165 °C [-85 –

329 °F], Brass, Gold

View on TE.com >



#### Connectors > RF Connectors > Coax Connectors











RF Interface: SMB

RF Connector Style: Jack

RF Connector Mated Outer Diameter (Approximate): 4.75 mm [ .187 in ]

Impedance:  $50 \Omega$ 

RF Connector Coupling Mechanism: Snap-Fit

# **Features**

# Product Type Features

Connector Shape	Rectangular
Connector Product Type	Connector Assembly
RF Interface	SMB
RF Connector Style	Jack
Connector System	Cable-to-Cable
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

# **Configuration Features**

PCB Mount Orientation	Vertical
Number of Positions	1
Number of Coaxial Contacts	1

### **Electrical Characteristics**

Impedance	50 Ω	
·		

# **Body Features**



RF Connector Center Contact Material  Brass  Ermination Features  Fermination Method to PCB  Surfa  echanical Attachment  RF Connector Coupling Mechanism  Snap  Connector Mounting Type  Board	d (Au) s ace Mount
Connector Center Contact Plating Material Gold RF Connector Center Contact Material Brass  Permination Features  Fermination Method to PCB Surfa  Pechanical Attachment  RF Connector Coupling Mechanism Snap  Connector Mounting Type Board  RF Contact Captivation Method Mechanism Mechanism Mechanism Mechanism Mechanism	d (Au) s ace Mount o-Fit
RF Connector Center Contact Plating Material  RF Connector Center Contact Material  Brass  ermination Features  Fermination Method to PCB  Surfa  echanical Attachment  RF Connector Coupling Mechanism  Snap  Connector Mounting Type  Board  RF Contact Captivation Method  Mechanism  Mechanism  Mechanism  Mechanism  Mechanism  RF Contact Captivation Method  Mechanism  Mechani	ace Mount o-Fit
RF Connector Center Contact Material  Brass  Ermination Features  Fermination Method to PCB  Surfa  echanical Attachment  RF Connector Coupling Mechanism  Snap  Connector Mounting Type  Board  RF Contact Captivation Method  Mechanism	ace Mount o-Fit
Fermination Features  Fermination Method to PCB  Surfa  echanical Attachment  RF Connector Coupling Mechanism  Snap  Connector Mounting Type  Board  RF Contact Captivation Method  Mechanism	ace Mount o-Fit
Fermination Method to PCB  surface  echanical Attachment  RF Connector Coupling Mechanism  Snap  Connector Mounting Type  Board  RF Contact Captivation Method  Mechanism	o-Fit
echanical Attachment  RF Connector Coupling Mechanism  Connector Mounting Type  RF Contact Captivation Method  Mechanical Attachment  Snap  Board  Mechanical Attachment  Snap	o-Fit
RF Connector Coupling Mechanism  Connector Mounting Type  Board  RF Contact Captivation Method  Mech	
Connector Mounting Type  RF Contact Captivation Method  Mech	
RF Contact Captivation Method Mech	rd Mount
	G IVICALIC
Detent	hanical
	out
imensions	
Product Length 7.7 m	nm[.303 in]
Profile Height from PCB 7.7 m	nm[.303 in]
RF Connector Mated Outer Diameter (Approximate) 4.75	mm[.187 in]
sage Conditions	
Operating Temperature Range -65 –	- 165 °C[-85 – 329 °F]
peration/Application	
Operating Frequency 4 GH	-lz
ackaging Features	
Packaging Quantity 100	
Packaging Method Tray	
ther	
Additional Features Pin P	Protection
Grade Profe	essional
Dielectric Material PTFE	

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant with Exemptions
EU ELV Directive 2000/53/EC	Not Compliant



China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) SVHC > Threshold: Pb (3.23% in 4867012) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**





# Customers Also Bought











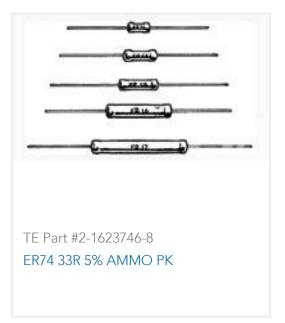












# **Documents**

# **Product Drawings**

SMB SMT Skt 50Ohm Gold Pltd

English

### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-1337604-0\_D.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-1337604-0\_D.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-1337604-0\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.